

POLOS® SPIN300x ADVANCED SPIN COATER

The POLOS® SPIN300x is a high-capacity spin processor engineered for exceptional process consistency, coating uniformity, and operational control. Designed exclusively as an Advanced configuration, this system builds on the proven SPINx platform and is constructed from Natural Polypropylene (NPP), with an optional PTFE version available for chemically aggressive applications.



Optimized for demanding R&D and production environments, the SPIN300x vacuum spin coater supports round wafers up to 300 mm in diameter as well as square substrates up to 200 × 200 mm, making it an ideal solution for large-format processing and scalable workflows.

UNIQUE, MODULAR DESIGN

The system's outer housing and integrated drain architecture enable easy conversion between tabletop operation and in-deck installation. Its modular construction supports a broad selection of accessories, allowing users to simplify dispensing, improve ergonomics, and future-proof the system as process requirements evolve.

AUTOMATION-READY BY DESIGN

As part of the SPINx series, the SPIN300x is built with automation in mind. Programmable motor homing positions enable precise alignment with robotic wafer handling systems for smooth integration in automated or semi-automated setups. The raised vacuum chuck sits above the bowl rim, giving clear access to the substrate and allowing safe, efficient handling with tweezers, vacuum wands, or robotic end-effectors.

AUTOMATIC LID OPERATION

The lid can be opened and closed automatically via the touch-screen interface or an optional foot pedal, ideal for glovebox or hands-free operation. The lid can also be programmed to open automatically at the end of a recipe, streamlining workflows and improving throughput.

LIQUID FILTER TRAP

To protect critical components, the SPIN300x features a liquid filter trap between the process chamber and vacuum lines. It captures accidental fluid ingress before it can reach key parts like the drive unit, vacuum sensor, valve, or ServoBL Controller. Collected liquid is stored in a removable container visible through a side window for quick inspection during routine maintenance.

CONFIGURATION

Process chamber material	Natural polypropylene (NPP) or PTFE (optionally)
Max. substrate diameter	Up to 12" (300 mm) wafers Up to 8" x 8" (200 mm) substrates
Indirect brushless drive unit	Up to 8,000 RPM
Acceleration	1 - 8,000 RPM (unloaded)

SUITABLE FOR:

- Coating
- Cleaning
- Rinse/Dry
- Developing
- Etching
- PDMI and other processes

STANDARD ACCESSORIES:

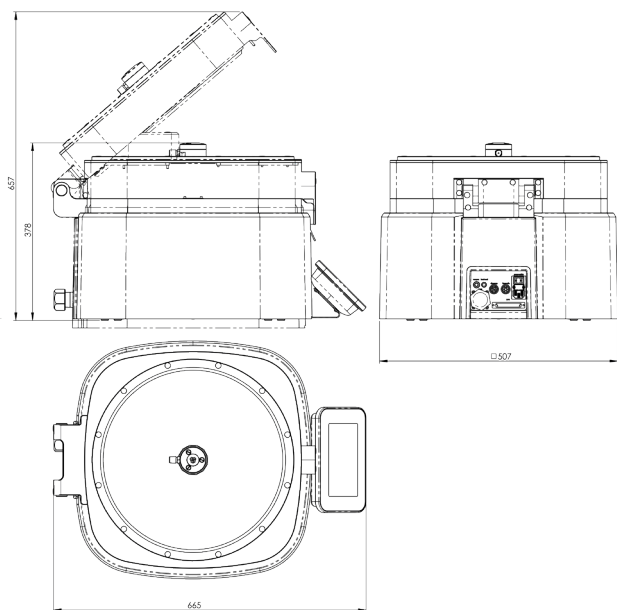
- Vacuum chuck for 12-inch wafers

SPIN COATING

SPECIFICATIONS SPIN300X ADVANCED

MODEL	SPIN300x ADVANCED
Liquid filter trap	Yes
Unique outer shell and drain design	Yes
Programmable motor home position	Yes
Center injection holder for syringe or dispense nozzle	Yes
Lid lock and vacuum sensor for user safety	Yes
Automatic lid, also controllable via foot pedal	Yes
Clockwise/counter clockwise rotation and puddle mode	Yes
Large (detachable) touchscreen display	Yes
USB port to store recipes on USB drive	Yes
Available in chemical resistant PTFE	Yes
Dispense vessel	Yes (optional)
Linear dispense arm	Yes (optional)
Backside rinse	Yes (optional)

DIMENSIONS SPIN300x



Unique outer/inner shell and drain design allows switch between table-top and in-deck model

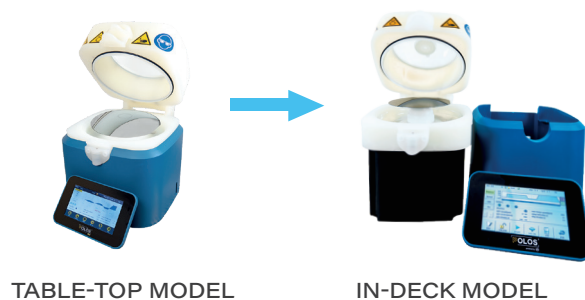


TABLE-TOP MODEL

IN-DECK MODEL

OPTIONS



Centering tool

POLOS®
Vacuum pumpPTFE Dispense
Vessel

And more. Contact us for all options!